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25th Anniversary

Preliminary Call for Papers www.ieeeicm2013.org

15 – 18 December 2013, Beirut - Lebanon





The International Conference on Microelectronics has been held in numerous countries across the Middle East and Asia over the past 24 years. The 25th edition of the conference will be held in Beirut, Lebanon. You are invited to celebrate with us the 25th anniversary. ICM 2013 will include oral, poster sessions and tutorials given by experts in state-of-the-art topics. The regular technical program will run for three days. In addition, tutorial sessions will be held on the first day of the conference. Papers are solicited in, but not limited to, the following topics:

Circuits and Systems (Coordinator: Oussama Bazzi - Lebanese University, Beirut, Lebanon)

- 1. Analog and RF circuit design techniques
- 2. Digital signal and data processing
- 3. Wireless communication systems
- 4. Nonlinear circuits
- 5. System on Chip (SoCs)
- 6. VLSI for Signal and Image Processing
- 7. Integrated antenna and front-end co-design
- 8. Signal Processing in Communications.

CAD Tools and Design (Coordinator: Tilda Akiki - Université Saint-Esprit Kaslik, Lebanon)

- 1. Simulation (process, device, circuit, logic, timing, functional)
- 2. Layout (placement, routing, floor planning, symbolic, ERC, DRC)
- 3. Silicon optimization
- 4. Parallel embedded systems
- 5. Testing: Formal verification
- 6. CAD for FPGAs
- 7. High level synthesis tools
- 8. Design for testability.

Micro/Nanoelectronics (Coordinator: Elias Rachid - Université Saint-Joseph, Lebanon)

- 1. Device characterization and modelling
- 2. Device physics and novel structures
- 3. Process technology, CMOS, BJT,
- 4. BiCMOS, GaAs
- 5. Reliability and failure analysis
- 6. Optoelectronics
- 7. MEMS Devices
- 8. Packaging and surface mount technology.

Special Session

Topic I: Optical communications

Topic II: Emerging biomedical wearable instrumenations

Topic III: Renewable Energy

Perspective authors are invited to submit full-length (4 pages) papers, in IEEE format, using the guidelines in the authors' info. Only electronic submissions will be accepted via the online submission system. Accepted papers will be published in the electronic Conference Proceedings (CD ROM) and included in IEEE XPLORE database.

Deadlines

Full Paper Submission : July 15, 2013
 Notification of Acceptance : September 16, 2013
 Camera Ready Submission : October 11, 2013





















